



Product Summary

VDSS	R _{DS(ON)}	Qg	Q _{gd}	ID
12V	18mΩ	3.2nC	0.3nC	4.8A

Typ. @ V_{GS} = 4.5V, T_A = +25°C

Description

This 2nd generation Lateral MOSFET (LD-MOS) is engineered to minimize on-state losses and switch ultra-fast, making it ideal for high efficiency power transfer. It uses Chip-Scale Package (CSP) to increase power density by combining low thermal impedance with minimal RDS(ON) per footprint area.

Applications

- DC-DC converters
- Battery management
- Load switches

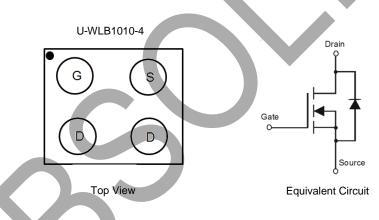
N-CHANNEL ENHANCEMENT MODE MOSFET

Features

- LD-MOS Technology with the Lowest Figure of Merit: R_{DS(ON)} = 18mΩ to Minimize On-State Losses Q_g = 3.2nC for Ultra-Fast Switching
- V_{GS(th)} = 0.8V Typ. for a Low Turn-On Potential
- CSP with Footprint 1.0mm × 1.0mm
- Height = 0.62mm for Low Profile
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Qsuffix) part. A listing can be found at https://www.diodes.com/products/automotive/automotiveproducts/.
- This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.
 <u>https://www.diodes.com/quality/product-definitions/</u>

Mechanical Data

- Package: U-WLB1010-4
- Terminal Connections: See Diagram Below



Ordering Information (Note 4)

Part Number	Paakaga	Pac	king
Part Number	Package	Qty.	Carrier
DMN1032UCB4-7	U-WLB1010-4	3,000	Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information



 $\begin{array}{l} MW = Product Type Marking Code \\ YM = Date Code Marking \\ Y \ or \ \underline{Y} = Year \ (ex: \ J = 2022) \end{array}$ M or \overline{M} = Month (ex: 9 = September)

Date Code Key

Code A J K L M N O P R S T Month Jan Feb Mar Apr May Jun Jul Aug Sep Oct Nov Dec Code 1 2 3 4 5 6 7 8 9 O N D	Year	2013		2022	2023	2024	2025	2026	2027	2028	2029	2030	2031
	Code	A		J	K	L	М	N	0	Р	R	S	Т
Code 1 2 3 4 5 6 7 8 9 O N D													
	Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	V _{DSS}	12	V		
Gate-Source Voltage			VGSS	±8	V
Continuous Drain Current (Note 5) V _{GS} = 4.5V	Steady State	T _A = +25°C T _A = +70°C	lo	4.8 3.8	А
Continuous Drain Current (Note 5) V _{GS} = 2.5V	Steady State	T _A = +25°C T _A = +70°C	lo	4.5 3.6	А
Pulsed Drain Current (Note 6)			Ідм	15	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 7)	PD	0.9	W
Thermal Resistance, Junction to Ambient $@T_A = +25^{\circ}C$ (Note 7)	Reja	138.81	°C/W
Thermal Resistance, Junction to Case @Tc = +25°C (Note 7)	Rejc	31.77	°C/W
Power Dissipation (Note 5)	PD	1.16	W
Thermal Resistance, Junction to Ambient @TA = +25°C (Note 5)	Reja	107.59	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

Notes:

Device mounted on FR4 material with 1inch² (6.45cm²), 2oz. (0.071mm thick) Cu.
 Repetitive rating, pulse width limited by junction temperature.
 Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.



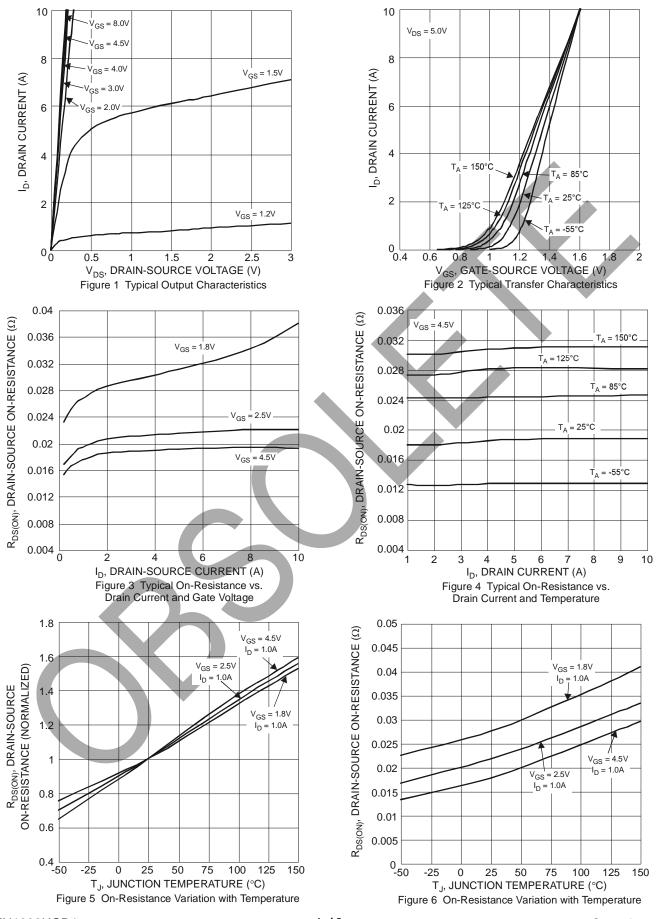
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)			51	1	1		
Drain-Source Breakdown Voltage	BVDSS	12	_	_	V	V _{GS} = 0V, I _D = 250µA	
Zero Gate Voltage Drain Current TJ = +25°C	IDSS	_	—	1.0	μA	V _{DS} = 9.6V, V _{GS} = 0V	
Gate-Source Leakage	lgss	_	_	±100	nA	$V_{GS} = \pm 8V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	VGS(th)	0.4	0.8	1.2	V	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	
		_	18	26		V _{GS} = 4.5V, I _D = 1A	
Static Drain-Source On-Resistance	RDS(ON)	_	21	29	mΩ	Vgs = 2.5V, Ip = 1A	
		_	27	38		V _{GS} = 1.8V, I _D = 1A	
Forward Transfer Admittance	Y _{fs}	_	8.1	_	S	Vps = 6V, Ip = 1A	
Diode Forward Voltage	Vsd	_	0.7	1.0	V	$V_{GS} = 0V, I_S = 1A$	
Reverse Recovery Charge	Qrr	_	1.2	_	nC	$V_{dd} = 5V$, $I_F = 1A$,	
Reverse Recovery Time	trr	_	10.5	—	ns	di/dt =100A/µs	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	Ciss	_	325	450			
Output Capacitance	Coss	_	183	250	pF	$V_{DS} = 6V, V_{GS} = 0V, f = 1MHz$	
Reverse Transfer Capacitance	Crss	_	31	47			
Series Gate Resistance	Rg	_	3.1	-	Ω	$f = 1MHz$, $V_{GS} = 0V$, $V_{DS} = 0V$	
Total Gate Charge	Qg	_	3.2	4.5		•	
Gate-Source Charge	Q _{gs}	s — 0.4 —		- 0			
Gate-Drain Charge	Q _{gd}	_	0.3	—	nC	$V_{GS} = 4.5V, V_{DS} = 6V, I_D = 1A$	
Gate Charge at Vth	Qg(th)	-	0.2				
Turn-On Delay Time	tD(on)	-	3.3	10			
Turn-On Rise Time	tr		5.6			$V_{DS} = 6V, V_{GS} = 4.5V,$	
Turn-Off Delay Time	tD(off)		24	36	ns	$R_G = 20\Omega$, $I_D = 1A$	
Turn-Off Fall Time	tf		9	—			

Notes:8. Short duration pulse test used to minimize self-heating effect.9. Guaranteed by design. Not subject to production testing.



DMN1032UCB4



DMN1032UCB4 Document number: DS36643 Rev. 8 - 4 4 of 8 www.diodes.com



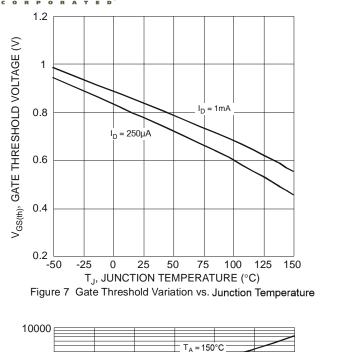
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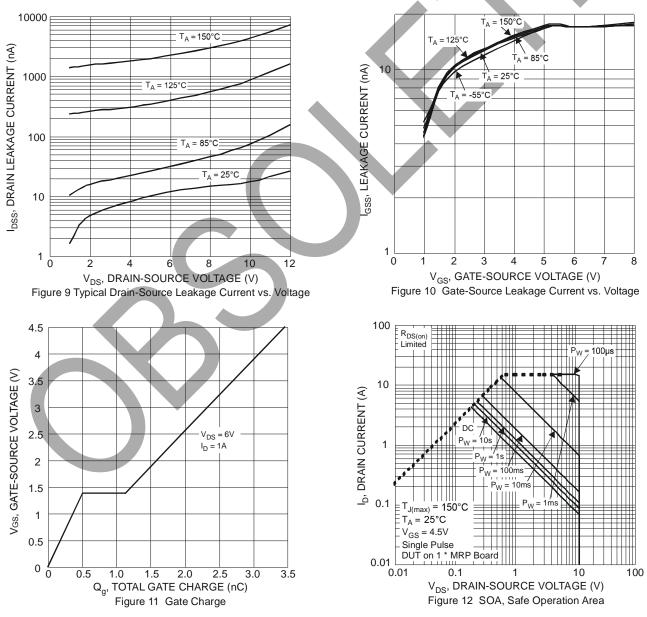
T_A = 25°C

T_A = -55°C

1.2

0.8





10

8

6

4

2

0_____

T_A = 150°C

T_A = 125°C

0.6

V_{SD}, SOURCE-DRAIN VOLTAGE (V)

Figure 8 Diode Forward Voltage vs. Current

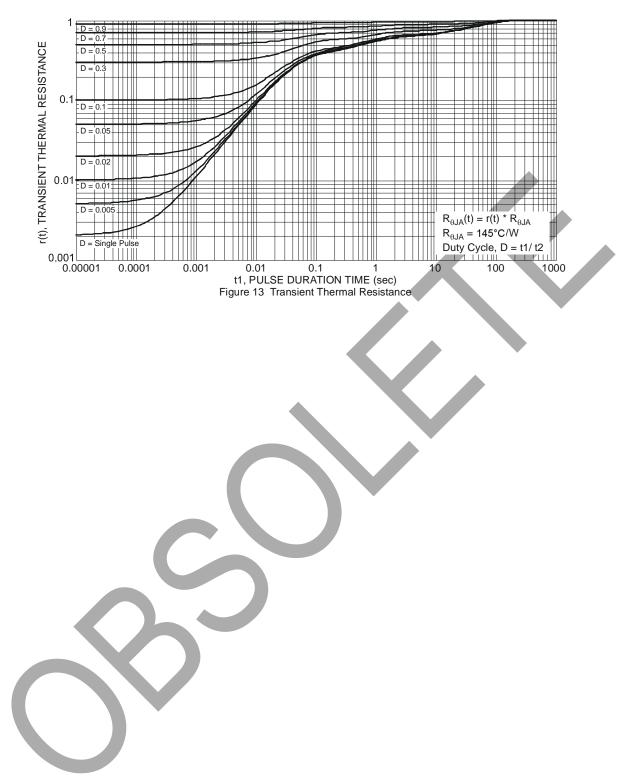
T_A = 85

0.4

I_S, SOURCE CURRENT (A)

DMN1032UCB4 Document number: DS36643 Rev. 8 - 4 5 of 8 www.diodes.com

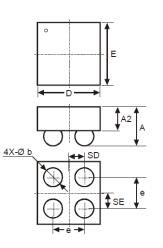






Package Outline Dimensions

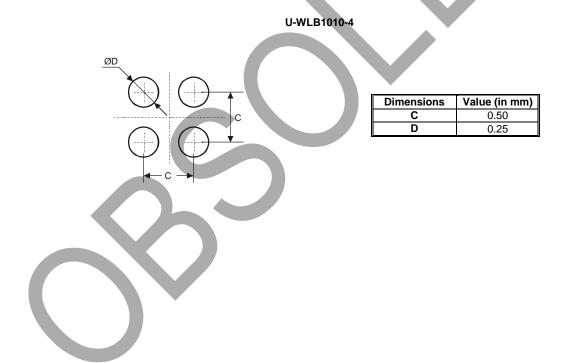
Please see http://www.diodes.com/package-outlines.html for the latest version.



Dim	Min	Max	Тур				
D	0.95	1.05	1.00				
Е	0.95	1.05	1.00				
Α	-	0.62	-				
A2	-	-	0.38	r			
b	0.25	0.35	0.30				
е	-	-	0.50				
SD	-		0.25				
SE	-	-	0.25				
All	Dimens	ions in I	nm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



U-WLB1010-4



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